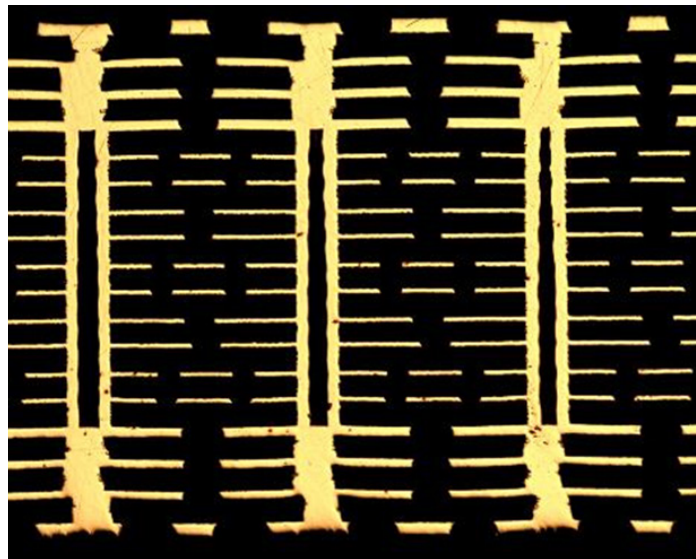


MacuSpec™ AVF 700

Advanced Copper Via Fill Metallization

Minimal Surface Copper Under a Wide Variety of Aspect Ratios

MacDermid Alpha's **MacuSpec AVF-700** is the choice when wide process windows and cost reduction are the goal. A unique formula of chemical components combined with operating settings enables customers to plate a wide variety of blind micro via sizes in just one bath. AVF-700 is perfect for applications such as Any Layer Buildup. Combined with MacDermid Alpha's industry leading direct metallization processes, AVF-700 is the most advanced via filling option available.



KEY FEATURES

- Excellent via filling of vias up to 7 mils in diameter and 4 mils deep with minimum surface copper
- Less than 15 μm surface copper under a wide variety of plating conditions
- Less / no copper reduction necessary after plating
- Fully analyzable by CVS and common analytical tools
- No flash plate required
- Compatible with the largest portfolio of direct metallization solutions worldwide
- Extraordinary repeatability while adhering to IPC 6012D 3.2.6.2 standard

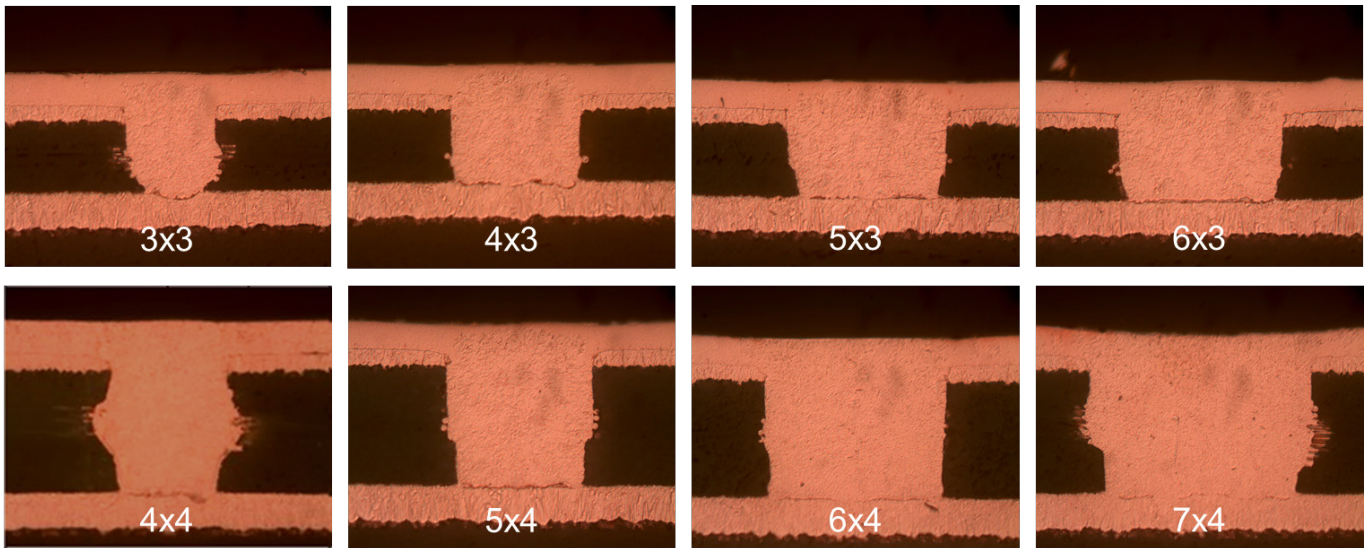


MacuSpec™ AVF 700

Advanced Via Fill Copper Metallization

Best in Class Copper Filling of Blind Micro Vias

The most advanced via filling chemistry available today, AVF-700 is able to fill a wide range of vias with as little as 12 microns and not more than 25 microns of surface copper while maintaining high quality deposit properties.



Reliable, High Quality Copper Vias, Every Single Time

Developed from combined industry experience, AVF-700 produces filled vias with an extraordinary degree of repeatability while adhering to IPC 6012D, 3.2.6.2. (Tensile strength no less than 36,000 psi and elongation no less than 12%). The improved copper on copper bonding provides reliability above and beyond that of what is expected from industry equivalents. Upgrade your via filling capability, save processing time, improve yields - install AVF-700.

